

# Precision Automation in Hermetic Package Sealing

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Precision automation is now possible when a deep understanding of the hermetic package sealing process is combined with current automation technology. Automatic sealing with exact fit covers provides the highest manufacturing yields and enables new package configurations to minimize board space needed for GEO, MEO and LEO satellites. Productivity increases are realized with the use of adaptive sealing on each individual package and the elimination of human intervention or complex jigs/fixtures specifically for the cover sealing process. When utilizing HSHD™ technology, changing over from one package type to another requires only a single PC program from a familiar GUI. Aerospace resistance weld power technology and proprietary electrodes provides for the widest margins on material sets, which are not always to specifications.